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## MXD8621EC

## SPDT Switch for 0.1~6.0GHz Application

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## General Description

The MXD8621EC is a Single-Pole, Double-Throw (SPDT) for $0.1 \sim 6.0 \mathrm{GHz}$ application. Switching is controlled by an integrated GPIO interface with a single control pin.

No external DC blocking capacitors are required as long as no DC voltage is applied on any RF path.

The MXD8621EC is provided in a compact 1.1 mm $\times 0.7 \mathrm{~mm} \times 0.377 \mathrm{~mm} 6$-lead DFN package that meets requirements for board-level assembly.

A functional block diagram and the pin configuration are shown in Figure 1.

## Applications

- GSM/WCDMA/LTE Receive
- WLAN TRX


## Features

- Broadband frequency range: 0.1 to 6.0 GHz
- Low insertion loss: 0.33 dB @ 2.7 GHz
0.55 dB @ 6.0 GHz
- High isolation: 38dB @ 2.7 GHz

30dB @ 6.0 GHz

- P0.1dB 29dBm
- No external DC blocking capacitors required
- Single GPIO control line with VDD voltage regulator:
$V_{D D}=1.62$ to 3.60 V
- Small, 6-Lead DFN, 400 um pitch (1.1mm x 0.7 mmx 0.377 mm ) package , MSL1


## Functional Block Diagram and Pin Function



Figure 1 Functional Block Diagram and Pin-out (Top View)

## Application Circuit



Figure 2 MXD8621EC Application Circuit

Table 1. Pin Description

| Pin No. | Name | Description | Pin No. | Name | Description |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 1 | RF2 | RF I/O. Throw 1 of the switch. | 6 | VC | Logic Control |
| 2 | GND | Ground | 5 | ANT | Antenna |
| 3 | RF1 | RF I/O. Throw 2 of the switch. | 4 | VDD | Supply |

## Truth Table

Table 2.

| State | Active Path | VC |
| :---: | :---: | :---: |
| 0 | ANT to RF1 | 0 |
| 1 | ANT to RF2 | 1 |

Note: "1" = 1.2 V to V DD V . "0" $=0 \mathrm{~V}$ to +0.3 V .

## Recommended Operation Range

Table 3.

| Parameters | Symbol | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Operation Frequency | f 1 | 0.1 | - | 6.0 | GHz |
| Power supply | $\mathrm{V}_{\mathrm{DD}}$ | 1.62 | 1.8 | 3.60 | V |
| Switch Control Voltage High | $\mathrm{V}_{\mathrm{CTL}} \mathrm{H}$ | 1.2 | 1.8 | $\mathrm{~V}_{\mathrm{DD}}$ | V |
| Switch Control Voltage Low | $\mathrm{V}_{\mathrm{CTL} \_\mathrm{L}}$ | 0 | 0 | 0.3 | V |

## Specifications

Table 4.Electrical Specifications

| Parameter | Symbol | Specification |  |  | Units | Test Condition |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Typical | Max. |  |  |
| DC Specifications |  |  |  |  |  |  |
| Supply voltage | VDD | 1.62 | 1.8 | 3.60 | V |  |
| Control voltage: Low <br> High | Vctl L <br> $V_{\text {ctil }}$ | $\begin{array}{r} 0 \\ 1.2 \\ \hline \end{array}$ | $\begin{array}{r} 0 \\ 1.8 \\ \hline \end{array}$ | $\begin{aligned} & 0.3 \\ & V_{D D} \end{aligned}$ | $\begin{aligned} & \mathrm{V} \\ & \mathrm{~V} \end{aligned}$ | , |
| Current on VC pin | Ictl |  |  | 5 | $\mu \mathrm{A}$ |  |
| Supply current | IDD |  | 100 | 140 | $\mu \mathrm{A}$ | $\mathrm{V}_{\mathrm{DD}}=1.8 \mathrm{~V}$ |
| DC supply turn-on/turn-off time | ton |  |  | 10 | $\mu \mathrm{s}$ | Measured from 50\% of final $V_{D D}$ supply voltage to $90 \%$ of final RF power |
| RF path switching time | tsw |  | 130 | 200 | ns | From one active state to another active state transition, measured from $50 \%$ of final control voltage to $90 \%$ of final RF power |
| Supply ripple | VPP |  |  | 50 | mV ppp |  |
| RF Specifications |  |  |  |  |  |  |
| Insertion loss (RF1 or RF2 to ANT pin) | IL |  | $\begin{aligned} & \hline 0.28 \\ & 0.30 \\ & 0.33 \\ & 0.40 \\ & 0.55 \\ & \hline \end{aligned}$ | $\begin{aligned} & \hline 0.35 \\ & 0.40 \\ & 0.45 \\ & 0.50 \\ & 0.65 \\ & \hline \end{aligned}$ | dB dB dB dB dB | 700 to 960 MHz 1710 to 2170 MHz 2170 to 2690 MHz 3600 to 3800 MHz 4800 to 6000 MHz |
| Isolation (ANT to RF1 or RF2) | ISO | $\begin{aligned} & 50 \\ & 42 \\ & 35 \\ & 31 \\ & 27 \\ & \hline \end{aligned}$ | $\begin{aligned} & 56 \\ & 45 \\ & 38 \\ & 34 \\ & 30 \\ & \hline \end{aligned}$ |  | $\begin{aligned} & \mathrm{dB} \\ & \mathrm{~dB} \\ & \mathrm{~dB} \\ & \mathrm{~dB} \\ & \mathrm{~dB} \end{aligned}$ | 700 to 960 MHz 1710 to 2170 MHz 2170 to 2690 MHz 3600 to 3800 MHz 4800 to 6000 MHz |
| Isolation (RF1 to RF2) | ISO | $\begin{aligned} & 49 \\ & 41 \\ & 34 \\ & 30 \\ & 26 \\ & \hline \end{aligned}$ | $\begin{array}{r} 55 \\ 44 \\ 37 \\ 33 \\ 29 \\ \hline \end{array}$ |  | $\begin{aligned} & \mathrm{dB} \\ & \mathrm{~dB} \\ & \mathrm{~dB} \\ & \mathrm{~dB} \\ & \mathrm{~dB} \\ & \hline \end{aligned}$ | 700 to 960 MHz 1710 to 2170 MHz 2170 to 2690 MHz 3600 to 3800 MHz 4800 to 6000 MHz |
| Input return loss (ANT to RF1 or RF2) | RL | 13 | 20 |  | dB | 700 to 6000 MHz |
| Voltage Standing Wave Ratio, all ports | VSWR |  | 1.25:1 | 1.5:1 | - | $\begin{aligned} & \text { Referenced to } 50 \Omega \text {, } \\ & 700 \text { to } 6000 \mathrm{MHz} \end{aligned}$ |
| 0.1 dB compression point ( from antenna to RF1 and RF2 ) |  | 29 |  |  | dBm | 700 M to 6000 MHz $25 \%$ duty pulse |
| 2nd Harmonic (ANT to RF1 or RF2) | 2 fo |  | -62 | -55 | dBm | $\mathrm{fo}=950 \mathrm{MHz}$ PIN $=+26 \mathrm{dBm}$ |
| 3rd Harmonic (ANT to RF1 or RF2) | 3fo |  | -62 | -55 | dBm | $\mathrm{fo}=950 \mathrm{MHz}, \mathrm{PIN}=+26 \mathrm{dBm}$ |
| 2nd Intermodulation Distortion | IMD2 |  | -103 | -100 | dBm | Two-tone test : $\mathrm{f} 0=24 \mathrm{dBm}$ and $\mathrm{f} 1=-$ |
| 3rd Intermodulation Distortion | IMD3 |  | -103 | -100 | dBm | 15 dBm at $\mathrm{f} 0+1 \mathrm{MHz}$ |

## Absolute Maximum Ratings

Table 5. Maximum ratings

| Parameters | Symbol | Minimum | Maximum | Units |
| :---: | :---: | :---: | :---: | :---: |
| Supply voltage | VDD | +1.62 | +3.7 | V |
| Digital control voltage | $\mathrm{V}_{\text {cti }}$ | 0 | +3.7 | V |
| RF input power | Pin |  | +30 | dBm |
| Operating temperature | Top | -40 | +85 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | Tstg | -55 | +150 | ${ }^{\circ} \mathrm{C}$ |
| Humidity Grade |  | MSL1 |  |  |
| Storage Cycle(package) |  | 2 |  | years |
| Electrostatic Discharge <br> Human body model (HBM), Class 1C <br> Machine Model (MM), <br> Class A <br> Charged device model (CDM), Class III | $\begin{aligned} & \text { ESD_HBM } \\ & \text { ESD_MM } \\ & \text { ESD_CDM } \end{aligned}$ |  | 1000 <br> 100 <br> 500 | V |

Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

Package Outline Dimension


Figure 3. Package outline dimension

Marking Specification


Figure 4 Marking specification (Top View)

## Tape and Reel Dimensions



Figure 5 Tape and reel dimensions

## Minimum packing Quantity

The minimum packing quantity of this device is 10000 .

## Reflow Chart



Figure 6. Recommended Lead-Free Reflow Profile
Table 6.

| Profile Parameter | Lead-Free Assembly, Convection, IR/Convection |
| :--- | :--- |
| Ramp-up rate $\left(\mathrm{TS}_{\text {max }}\right.$ to $\left.\mathrm{T}_{\mathrm{p}}\right)$ | $3^{\circ} \mathrm{C} /$ second max. |
| Preheat temperature $\left(\mathrm{TS}_{\min }\right.$ to $\left.\mathrm{TS}_{\max }\right)$ | $150^{\circ} \mathrm{C}$ to $200^{\circ} \mathrm{C}$ |
| Preheat time $\left(\mathrm{t}_{\mathrm{s}}\right)$ | $60-180$ seconds |
| Time above $\mathrm{TL}, 217^{\circ} \mathrm{C}\left(\mathrm{t}_{\mathrm{L}}\right)$ | $60-150$ seconds |
| Peak temperature $\left(\mathrm{T}_{\mathrm{p}}\right)$ | $260^{\circ} \mathrm{C}$ |
| Time within $5^{\circ} \mathrm{C}$ of peak temperature $\left(\mathrm{t}_{\mathrm{p}}\right)$ | $20-40$ seconds |
| Ramp-down rate | $66^{\circ} \mathrm{C} /$ second max. |
| Time $25^{\circ} \mathrm{C}$ to peak temperature | 8 minutes max. |

## ESD Sensitivity

Integrated circuits are ESD sensitive and can be damaged by static electric charge. Proper ESD protection techniques should be used when handling these devices.

## RoHS Compliant

This product does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), and are considered RoHS compliant.

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